BCP53T1 Series

Preferred Devices

PNP Silicon Epitaxial Transistors

This PNP Silicon Epitaxial transistor is designed for use in audio amplifier applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

- High Current: 1.5 Amps
- NPN Complement is BCP56
- The SOT-223 Package can be soldered using wave or reflow. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die
- Available in 12 mm Tape and Reel Use BCP53T1 to order the 7 inch/1000 unit reel. Use BCP53T3 to order the 13 inch/4000 unit reel.
- Device Marking: BCP53T1 = AH BCP53-10T1 = AH-10 BCP53-16T1 = AH-16
- Pb–Free Package May be Available. The G–Suffix Denotes a Pb–Free Lead Finish

MAXIMUM RATINGS (T_C = 25° C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	VCEO	-80	Vdc
Collector-Base Voltage	VCBO	-100	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current	IC	1.5	Adc
Total Power Dissipation @ T _A = 25°C (Note 1.) Derate above 25°C	PD	1.5 12	Watts mW/°C
Operating and Storage Temperature Range	TJ, Tstg	–65 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient (surface mounted)	R _{θJA}	83.3	°C/W
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	ΤL	260 10	°C Sec

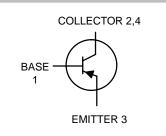
1. Device mounted on a glass epoxy printed circuit board 1.575 in. x 1.575 in. x 0.059 in.; mounting pad for the collector lead min. 0.93 sq. in.



ON Semiconductor®

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MEDIUM POWER HIGH CURRENT SURFACE MOUNT PNP TRANSISTORS



MARKING DIAGRAM



SOT-223 CASE 318E STYLE 1

 $\begin{array}{ll} \mathsf{AHxxx} &= \mathsf{Device} \; \mathsf{Code} \\ \mathsf{xxx} &= -10 \; \mathsf{or} \; -16 \end{array}$

ORDERING INFORMATION

Device	Package	Shipping [†]
BCP53T1	SOT-223	1000/Tape & Reel
BCP53T1G	SOT-223 (Pb-Free)	1000/Tape & Reel
BCP53-10T1	SOT-223	1000/Tape & Reel
BCP53-16T1	SOT-223	1000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Min	Тур	Max	Unit
V(BR)CBO	-100	-	-	Vdc
V(BR)CEO	-80	-	-	Vdc
V(BR)CER	-100	-	-	Vdc
V(BR)EBO	-5.0	-	-	Vdc
ICBO	-	-	-100	nAdc
IEBO	-	-	-10	μAdc
	V(BR)CBO V(BR)CEO V(BR)CER V(BR)EBO ICBO	V(BR)CBO -100 V(BR)CEO -80 V(BR)CER -100 V(BR)EBO -5.0 ICBO -	V(BR)CBO -100 - V(BR)CEO -80 - V(BR)CER -100 - V(BR)EBO -5.0 - ICBO - -	V(BR)CBO -100 - - V(BR)CEO -80 - - V(BR)CER -100 - - V(BR)EBO -5.0 - - ICBO - - -

ON CHARACTERISTICS

DC Current Gain ($I_C = -5.0$ mAdc, $V_{CE} = -2.0$ Vdc) All Part Types ($I_C = -150$ mAdc, $V_{CE} = -2.0$ Vdc) BCP53T1 BCP53-10T1 BCP53-10T1 ($I_C = -500$ mAdc, $V_{CE} = -2.0$ Vdc) All Part Types	hFE	25 40 63 100 25	- - - -	- 250 160 250 -	_
Collector-Emitter Saturation Voltage ($I_C = -500$ mAdc, $I_B = -50$ mAdc)	VCE(sat)	_	_	-0.5	Vdc
Base-Emitter On Voltage (I _C = -500 mAdc, V _{CE} = -2.0 Vdc)	V _{BE(on)}	-	-	-1.0	Vdc
DYNAMIC CHARACTERISTICS					

DYNAMIC CHARACTERISTICS

Current-Gain – Bandwidth Product ($I_C = -10 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}, f = 35 \text{ MHz}$)	fT	-	50	-	MHz



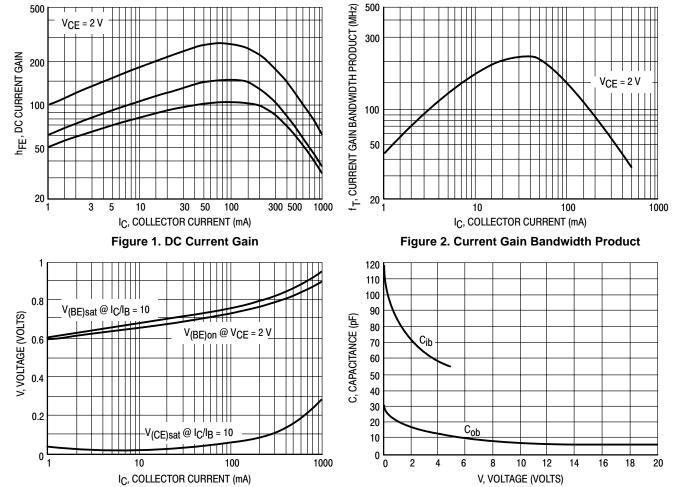
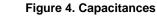
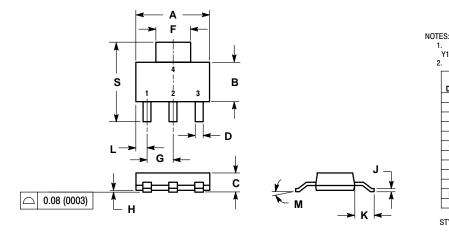


Figure 3. Saturation and "ON" Voltages



PACKAGE DIMENSIONS

SOT-223 CASE 318E-04 ISSUE K



	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.249	0.263	6.30	6.70
В	0.130	0.145	3.30	3.70
С	0.060	0.068	1.50	1.75
D	0.024	0.035	0.60	0.89
F	0.115	0.126	2.90	3.20
G	0.087	0.094	2.20	2.40
н	0.0008	0.0040	0.020	0.100
J	0.009	0.014	0.24	0.35
Κ	0.060	0.078	1.50	2.00

0.85

0 ° 10 °

6.70

1.05

7.30

DIMENSIONING AND TOLERANCING PER ANSI

 M
 0 °
 10 °

 S
 0.264
 0.287
STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

L 0.033 0.041

1.

SOLDERING FOOTPRINT*

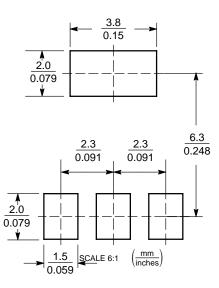


Figure 5. SOT-223

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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